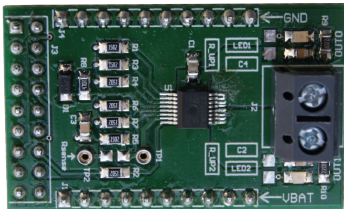


VND7E040AJ evaluation board



GAPG170414105ZCF1

Features

| | | |
|--|---------------------|---------------|
| Max transient supply voltage | V_{CC} | 40 V |
| Operating voltage range | V_{CC} | 4 to 28 V |
| Typ. on-state resistance (per Ch) | R_{ON} | 38 m Ω |
| Current limitation (typ) | I_{LIMH} | 38 A |
| Stand-by current (max) | I_{STBY} | 0.5 μ A |
| Minimum cranking supply voltage (V_{CC} decreasing) | $V_{USD_cranking}$ | 2.85 V |

- Simple single IC application board dedicated for VND7E040AJ
- Provides electrical connectivity and thermal heat-sinking for easy prototyping
- General device features
 - Extreme low voltage operation for deep cold cranking applications (compliant to LV124, revision 2013)
 - Double channel smart high-side driver with CurrentSense analog feedback
 - Very low standby current
 - Compatible with 3 V and 5 V CMOS outputs
- Diagnostic functions
 - Analog feedback of load current with high precision proportional current mirror
 - Overload and short to ground (power limitation) indication
 - Thermal shutdown indication
 - OFF-state open-load detection
 - Output short to V_{CC} detection
 - Sense enable/disable
- Protections
 - Undervoltage shutdown
 - Overvoltage clamp
 - Load current limitation
 - Self limiting of fast thermal transients
 - Configurable latch-off on overtemperature or power limitation with dedicated fault reset pin
 - Loss of ground and loss of V_{CC}
 - Reverse battery with external components
 - Electrostatic discharge protection

Product status link

[EV-VND7E040AJ](#)

Product summary

| | |
|---------------|--------------------------------|
| EV-VND7E040AJ | VND7E040AJ evaluation board |
|---------------|--------------------------------|

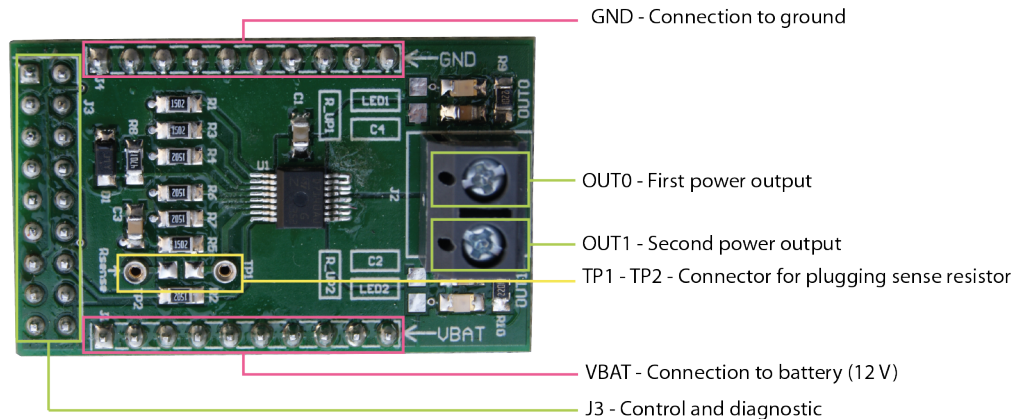
Applications

- Automotive resistive, inductive and capacitive loads
- Protected supply for ADAS systems: radars and sensors
- Automotive headlamp

1 Board connections

Figure 2. Evaluation board connections shows the placement of the connectors to be used to supply the evaluation board, to connect the load and to control the functionality and diagnostic of the device.

Figure 2. Evaluation board connections



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Table 1. J3 connector: pin functions

| Connector | Pin number | Pin name | Pin function |
|-----------|------------|------------------------------|---|
| J3 | 1...4 | N/A | Not connected. |
| J3 | 5 | IN_PullUP | Connection to optional external pull-up resistor for open load detection in off-state. |
| J3 | 6 | +5V | 5 V Power Supply. |
| J3 | 7 | $\overline{\text{FaultRST}}$ | Active low compatible with 3 V and 5 V CMOS outputs pin; it unlatches the output in case of fault; If kept low, sets the outputs in auto-restart. |
| J3 | 8 | CurrentSense | Analog current sense output pin; delivers a current proportional to the selected load current. |
| J3 | 9 | S_EN | Active high compatible with 3 V and 5 V CMOS outputs pin; it enables the CurrentSense diagnostic pin. |
| J3 | 10 | SEL0 | Active high compatible with 3 V and 5 V CMOS outputs pin; together with SEL1, it addresses the CurrentSense multiplexer. |
| J3 | 11 | SEL1 | Active high compatible with 3 V and 5 V CMOS outputs pin; together with SEL0, it addresses the CurrentSense multiplexer. |
| J3 | 12 | N/A | Not connected. |
| J3 | 13 | IN0 | Voltage controlled input pin with hysteresis, compatible with 3 V and 5 V CMOS outputs. It controls OUT0 switch state. |
| J3 | 14 | IN1 | Voltage controlled input pin with hysteresis, compatible with 3 V and 5 V CMOS outputs. It controls OUT1 switch state. |
| J3 | 15...18 | N/A | Not connected. |

In case the user wishes to use the CurrentSense/MultiSense function of the device, it is necessary to plug a sense resistor in R_{SENSE} .

The package includes a through-hole resistor, to be mounted on TP1-TP2 (see [Figure 4. Mounting through-hole sense resistor](#)).

Different R_{SENSE} values can be adopted based on user preference.

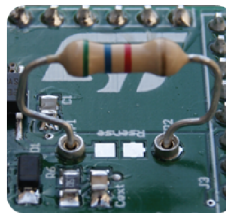
Another option is soldering an SMD resistor on the dedicated PCB pad, as shown in [Figure 5. Pads for soldering SMD resistor](#).

Figure 3. No sense resistor



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Figure 4. Mounting through-hole sense resistor



GAPG1004141007CFT

Figure 5. Pads for soldering SMD resistor



GAPG1004141008CFT

2 Thermal data

Table 2. Thermal data

| Symbol | Parameter | Max | Unit |
|----------------------|---|-----|------|
| R _{thj-amb} | Thermal resistance junction-ambient (max) | 39 | °C/W |

Table 3. PCB specifications

| Parameter | Value |
|-------------------------|-----------------|
| Board dimensions | 25 mm x 41.5 mm |
| Number of Cu layer | 2 |
| Layer Cu thickness | 35 μm |
| Board finish thickness | 1.6 mm +/- 10% |
| Board Material | FR4 |
| Thermal vias separation | 1.1 mm |
| Thermal vias diameter | 0.5 mm |

Revision history

Table 4. Revision history

| Date | Revision | Changes |
|-------------|----------|------------------|
| 02-Sep-2019 | 1 | Initial release. |

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